deprocessing, parallel mechanical polishing, FIB/SEM cross sectioning/imaging, OM, LCM, TEM, UHR-SEM, analytical TEM, EELS, EDS, STEM, SIMS, ESCA/XPS, EMPI, FMI, LSM-near IR, SOM (backside), TDR, FIB circuit edit (back/topside) with Ga/plasma beam, AFM, AES, FTIR, GC-MS, ICP-MS, Raman spectroscopy, XRD, XRR, WD-XRF, etc.

PRIORITY LABS
1001 S. Sherman St.
Richardson, TX 75081
Tel: 972.499.4756
e-mail: info@prioritylabs.com
Web: prioritylabs.com
Services: IC FA, materials analysis, counterfeit detection, etc.
Tools/Techniques: Deprocessing, decapsulation, TDR, electrical characterization, dye and pry, cross sectioning, SAM, optical inspection, x-ray, global isolation, SEM, FIB, etc.

SAGE ANALYTICAL LAB, LLC
Moe Homayounieh
6370 Nancy Ridge Dr., Suite 112
San Diego, CA 92121
Tel: 858.255.8587 or 949.338.2876
e-mail: Moe@sagefalab.com
Web: sagefalab.com
Services: PCB/package integrity evaluation and FA, IC circuit edit, FIB nanofabrication, electronic component DPA, competitor analysis/reverse engineering, comprehensive passive component FA, ESD/LU testing (HBM, MM, CDM), IC process consultation, quality control/evaluations, etc.

Tools/Techniques: 3-D/CT submicron x-ray, CSAM evaluation, precise submicron cross sectioning and substrate thinning/polishing, SEM analysis and imaging, EDS analysis, front and backside FIB, dye and pry, photoemission microscopy, LIVA, XIVA, OBIRCH, chemical/mechanical decapsulation, electrical characterization/microprobing, solder joint integrity, high-resolution IC/package photovisualization, chemical/mechanical deprocessing, etc.

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Web: scientiasilicon.co.uk
Services: Client-focused solutions for physical FA, constructional analyses, counterfeit device investigation, expert witness and consultation, semiconductor forensic recovery and repackaging
Tools/Techniques: Precision mechanical polishing/grinding (front and backside, cross section), SEM/EDX, FIB, CT, light microscopy, wire bonding

NOTEWORTHY NEWS

ITC 2016

The International Test Conference (ITC) will be held November 15 to 17, 2016, at the Fort Worth Convention Center in Fort Worth, Texas. ITC is the world’s premier conference dedicated to the electronic test of devices, boards, and systems and covers the complete cycle from design verification and validation, test, diagnosis, failure analysis, and back to process, yield, reliability, and design improvement. At ITC, test and design professionals can confront the challenges the industry faces and learn how these challenges are being addressed by the combined efforts of academia, design tool and equipment suppliers, designers, and test engineers.

ITC, the cornerstone of TestWeek events, offers a wide variety of technical activities targeted at test and design theoreticians and practitioners, including formal paper sessions, tutorials, panel sessions, case studies, a lecture series, commercial exhibits and presentations, and a host of ancillary professional meetings.

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